

# **ICAS: Integrated Circuits And Systems**

IMB-CNM (CSIC)

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### Mission Vision

Research and training on *Micro/Nano-Electronic Devices*, *Circuits and Systems Design, Test and Deploy* by means of SoA/new technologies, techniques and open architectures to improve the performances of multi-technology integrated solutions.

Improve, connect & exploit the new "micro/nano-devices" from different technologies within the "macro" framework of target end applications through smart interfaces developed including the appropriate degree of intelligence and moving to open hardware strategies and solutions.

#### **Group Profile**

## **Recent / Ongoing Results**

- Low-Power Analog, Mixed & RF CMOS
- IR/XRay Imagers
- Smart sensor frontends
- IP blocks (DAC/ADC, PLL, ...)
- Open hardware and RISC-V based dev.
- Printed/Organic-µelectronics
  - Inkjet Printed Technologies & Devices
  - Organic Thin Film Transistors and Sensors
  - Printed Flexible Circuits

- BrainCom (H2020-FETPROACT-Grant 732032): Cortical implants as braincomputer interfaces for cognitive neuroscience applications.
- EcoTronic (RTI2018-102070-B-C21): Disposable Paper Electronic Devices for Sustainable Eco-friendly Platforms.
- Red-RISCV (RED2018-102384-T): Investigación, Formación e Innovación en Sistemas RISC-V.
- Lagarto-RISC-V (BSC Contract): 1<sup>st</sup> Spanish-Mexican RISC-V processor on TSMC-65nm silicon chip (via Europractice).



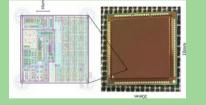
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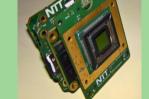
- Digital Design
- Microelectronic Design & Test
- Introduction to Computer architecture
- Informatics, Telecomunication & Electronics engineering degrees
- Micro/Nano-Electronics Engineering Master
- Mixed teaching courses: on-line (MOOC) & Classroom
- Publications:
- An Academic EDA Suite for the Full-Custom Design of Mixed-Mode Integrated Circuits, ISCAS-2017
- Digital Systems: from Logic Gates to Processors. Springer, 2017.
- Complex Digital Circuits. Springer 2019.
- UAB Engineering School: Hardware and Computer Architecture degree subjects updated & harmonized on a RISC-V basis (initial phase)



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- In the past lots of industry-based R&D
- Now better balanced "research&Industry"
- IR/XRay-ROICs for imagers
- IP-blocks/chips for SilTerra, Arquimea/ESA, NIT.
- More technology transfer to SMEs on printed-organic µelectronics
- Two IP-cores (Temperature sensor & Charge-pump) for SilTerra Co. SILTERRA
- Two ADC IP blocs designed for Arquimea/ESA consortium
- Three different IR-ROIC chip imagers (32x32, 80x80 and 128x128 pixels) transferred to NIT S.L.









## **Group positioning & Perspectives in front of Open-Hw & RISC-V**

- Open Hw/Sw reduces dependency and facilitates collaborative projects and competitive markets.
- Freedom for evolution and helpful for training & education of new generations of professionals on Open Hw/Sw.
- IP-Blocks design (PLL, ADC, SerDes, Memory Ctrl., ...) for RISC-V cores and related application developments.
- Low power RISC-V cores for IoT.
- Use RISC-V as innovator driver-thread for universities and collaborative training strategies for all education levels.
- Just starting an Industrial PhD around RISC-V core for IoT with NVision company

Global Remarks

"To consolidate the open hardware/software strategies based on the new RISC-V architectures, the synergies of the **prodigious circle "Research-Training-Innovation"** are required as an engine for a collaborative and joint evolution of the entire ecosystem that guarantees sustained, sustainable, cooperative and open progress "

"The new open ISA RISC-V architectures offer an opportunity to improve technological independence, reduce oligopoly risks and facilitate market open competition"



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Innovation

Research